

1.Description

SDT23C24L02 component is designed to protect sensitive electronics from damage or latch-up due to ESD and other voltage induced transient events. It is designed for use in applications where board space is at a premium. The device will protect up to two lines. It is bidirectional devices and may be used on lines where the signal polarities are above ground.

3.Features

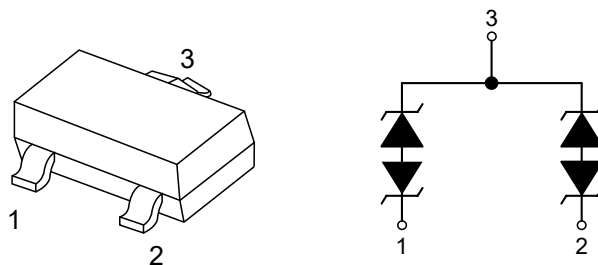
- IEC61000-4-2 ESD 15KV Air, 8KV contact compliance
- SOT-23 surface mount package
- Protects bidirectional two I/O lines
- Peak power dissipation of 350W under 8/20 μ s waveform

2.Applications

- RS-232 and RS-422 data lines
- Microprocessor based equipment
- LAN/WAN equipment
- Desktops PC and servers
- Notebook, Laptop and Palmtop computers
- Set Top Box
- Peripherals
- Serial and Parallel ports

- Working voltage: 24V
- Low leakage current
- Low operating and clamping voltages
- Solder reflow temperature: Pure Tin-Sn, 260~270°C

4.Pinning information



SOT-23



5. Absolute Maximum Ratings

Parameter	Symbol	Value	Units
Peak Pulse Power ($t_p=8/20\mu s$ waveform)	P_{PP}	350	W
ESD voltage (Contact discharge)	V_{ESD}	± 8	kV
ESD voltage (Air discharge)		± 15	kV
Storage & junction temperature range	T_J, T_{STG}	-55 to 150	$^{\circ}C$

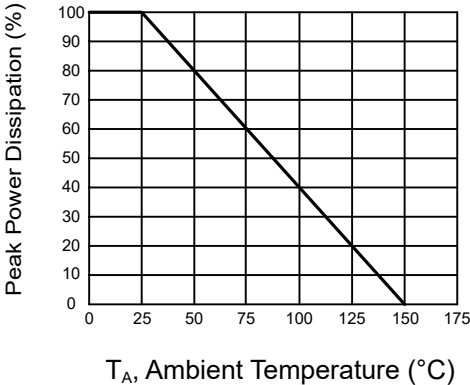
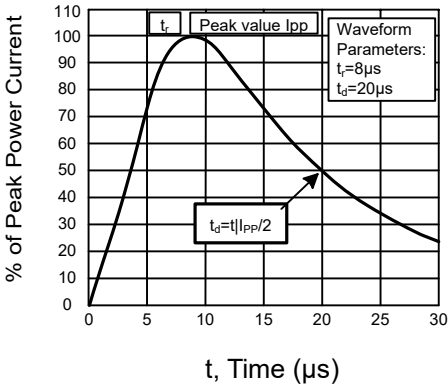
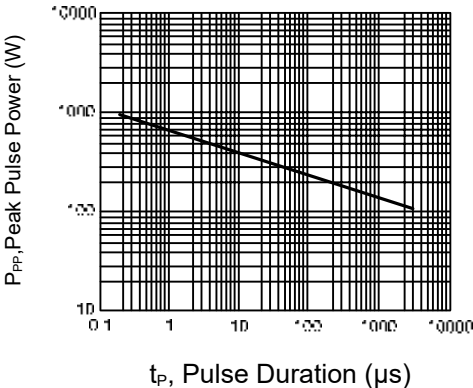
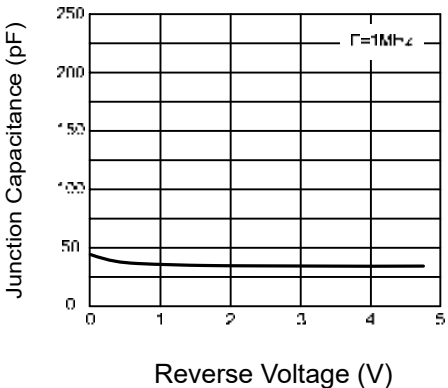


6. Electrical Characteristics ($T_J=25^{\circ}\text{C}$)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Reverse Stand-Off Voltage	V_{RWM}				24	V
Reverse Breakdown Voltage	V_{BR}	$I_{BR}=1\text{mA}$	26.7			V
Reverse Leakage Current	I_R	$V_R=24\text{V}$, Each I/O pin			1	μA
Clamping voltage ($t_p=8/20\mu\text{s}$)	V_C	$I_{PP}=1\text{A}$			43	V
Clamping voltage ($t_p=8/20\mu\text{s}$)	V_C	$I_{PP}=5\text{A}$			52	V
Off state junction capacitance	C_J	0Vdc, $f=1\text{MHz}$ Between I/O pins and GND		40		pF



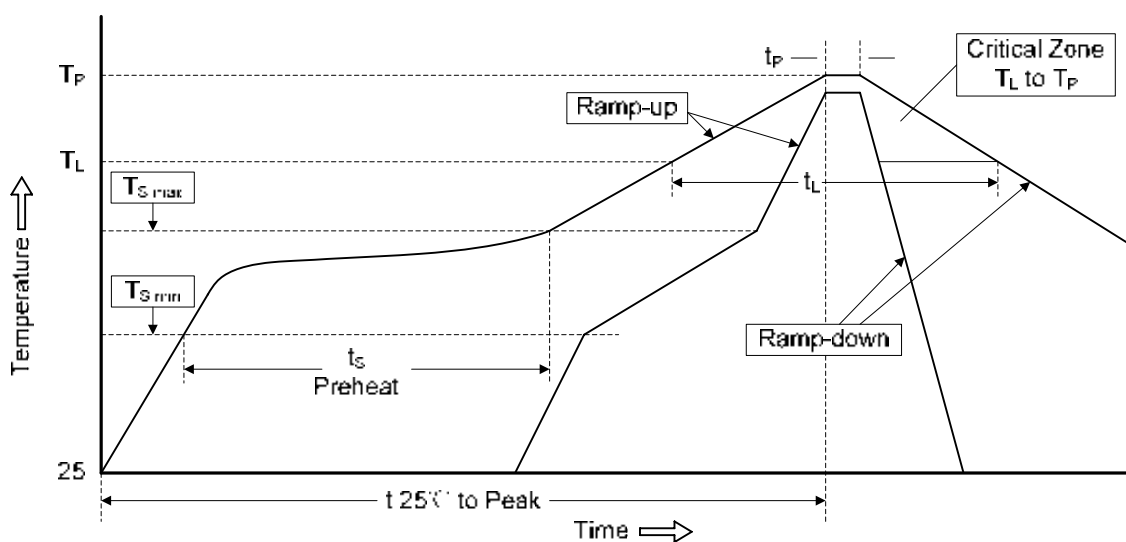
7. Typical characteristic

	
Figure 1: Power Derating Curve	Figure 2: Pulse Waveforms
	
Figure 3: Non-Repitative Peak Pulsevs. Pulse Time	Figure 4: Normalized Capacitance vs. Reverse Voltage



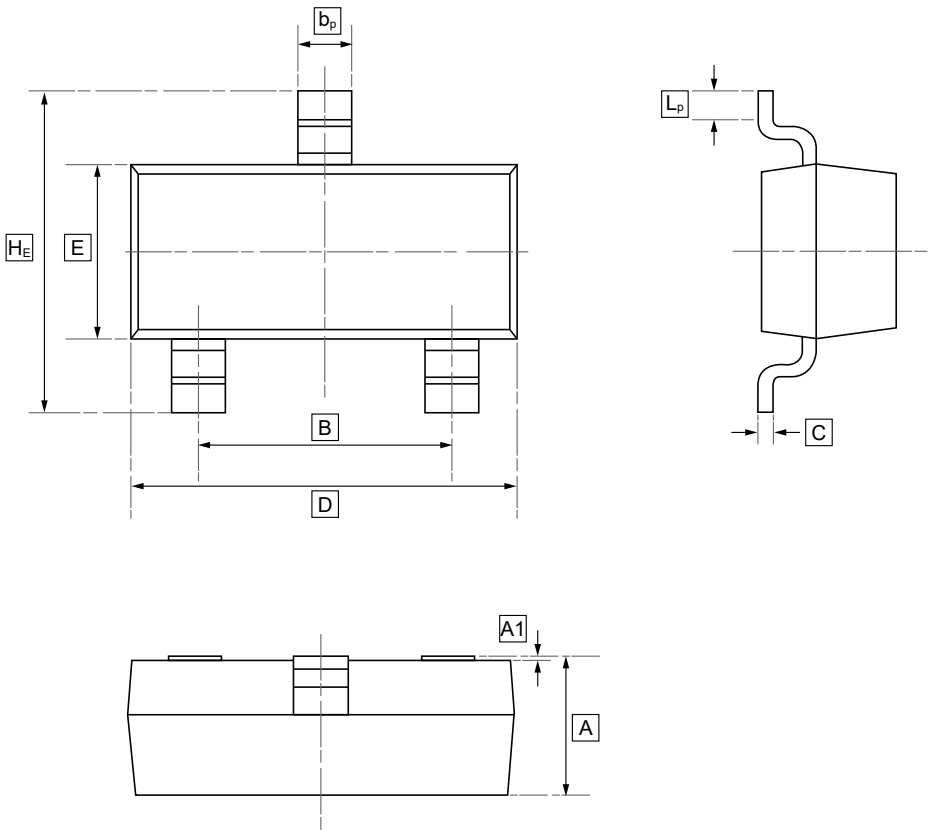
8. Recommended Soldering Conditions

Reflow Condition		Pb-Free Assembly
Pre Heat	-Temperature Min ($T_{s(min)}$)	150°C
	-Temperature Max ($T_{s(max)}$)	200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp-up rate (T_L to T_P)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Time maintained above:	-Temperature(T_L)	217°C
	-Time(T_L)	60-150 secs.
Peak Temp (T_P)		260°C
Time within 5°C of actual Peak Temp (T_P)		20-40 seconds
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temperature		8 min. Max





9.SOT-23 Package Outline Dimensions

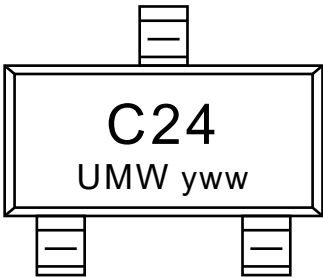


DIMENSIONS (mm are the original dimensions)

Symbol	A	B	b _p	C	D	E	H _E	A1	L _p
Min	0.95	1.78	0.35	0.08	2.70	1.20	2.20	0.013	0.20
Max	1.40	2.04	0.50	0.19	3.10	1.65	3.00	0.100	0.50



10.Ordering information



yww: Batch Code

Order Code	Package	Base QTY	Delivery Mode
UMW SDT23C24L02	SOT-23	3000	Tape and reel



11.Disclaimer

UMW reserves the right to make changes to all products, specifications. Customers should obtain the latest version of product documentation and verify the completeness and currency of the information before placing an order.

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